

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJB85SN08C
Package Type :	TO-263-2L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.000%	0.09%
Lead Frame	Cu	7440-50-8	99.900%	56.18%
	Fe	7439-89-6	0.060%	
	P	7723-14-0	0.037%	
	Ag	7440-22-4	0.003%	
Die Attach	Lead	7439-92-1	92.500%	0.46%
	Tin	7440-31-5	5.000%	
	silver	7440-22-4	2.500%	
Wire1	Al	7429-90-5	99.990%	0.21%
	others	—	0.010%	
Wire2	Al	7429-90-5	98.85%	0.13%
	Si	7440-21-3	1.15%	
Mold Compound	Epoxy resin A	Trade Secret	5.914%	42.84%
	Epoxy resin B	29690-82-2	3.870%	
	Phenol Resin	Trade Secret	2.198%	
	Silica(Amorphous) A	60676-86-0	80.508%	
	Silica(Amorphous) B	7631-86-9	6.880%	
	Carbon black	1333-86-4	0.630%	
Plating	Tin	7440-31-5	100.000%	0.09%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.